

Procedure file

Basic information					
DEA - Delegated acts procedure	2018/2947(DEA)	Procedure completed - delegated act enters into force			
Exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages					
Supplementing 2008/0240(COD)					
Subject					
3.40.06 Electronics, electrotechnical industries, ICT, robotics					
3.70.13 Dangerous substances, toxic and radioactive wastes (storage, transport)					
Documentation gateway					
Non-legislative basic document		C(2018)07499	16/11/2018	EC	